

Technical Data Sheet

FeedBond® EP-2006-SC5-6

Fast Cure Non-Conductive Adhesive

Introduction:

FeedBond®EP-2006-SC5-6 single component ,fast cure adhesive is designed for low modulus application. This adhesive can be fast cured using directed heat energy or hot plate curing techniques.

Characteristics:

- Snap cure, hot plate cure and oven cure
- Excellent dispensability
- Low modulus of elasticity

UNCURED PROPERTIES		TEST DESCRIPTION	TEST METHOD
Appearance	red		
Viscosity @ 25°C	10000±2000 cps	Brookfield DV-III/CP-51 @ 5rpm	FT-P006
Thixotropic Index @ 25°C	1.5~2.5	Brookfield DV-III/CP-51 Visc. @ 0.5rpm/Visc. @ 5rpm	FT-P008
Grind	< 20µm	Grind meter	FT-P026
Work Life @ 25°C	24 hrs	25% increase in visc. @ 5rpm	FT-P024
Shelf Life@ -40°C	6 months		FT-P018
CURE CONDITION		TEST DESCRIPTION	TEST METHOD
Standard Cure Condition		90sec on hot plate @110°C	
		10sec on hot plate @150°C	

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PHYSIOCHEMICAL PROPERTIES- POST CURE	TEST DESCRIPTION	TEST METHOD
Glass Transition Temperature (Tg) 46°C	DMA 3 Point Bending Mode	FT-M014
Coefficient of Thermal Expansion		
Below Tg(α_1) 25 ppm/°C	TMA Expansion Mode	FT-M016
Above Tg(α_2) 194 ppm/°C		
Storage Modulus		
@25°C 603MPa	Dynamic Mechanical Thermal	
@150°C 59MPa	Analysis using <1.6mm thick	FT-M019
@250°C 69MPa	specimen	
MECHANICAL PROPERTIES- CURE	TEST DESCRIPTION	TEST METHOD
Die Shear Strength @ 25°C >2kg/die	80mil × 80mil Si die on Ag LF Cure 90 sec on hot plate @110°C	FT-M012

p.s. The tables shown above are typical values only. If you need to write a specification, please request our current Standard Release Specification.

Instruction

This product is easy to hindered, resulting inhibit the cure. Avoid the following materials: ①Containing Amin type, Thiol type, acid anhydride. ② Alcohol, Ketone, Polar solvent (DME, NMP). ③The sulfur-containing surface treatment agent.

Thawing

Place the container to stand vertically for 30min ~90min. **DO NOT** open the container before adhesive reaches ambient temperature to prevent the moisture condensation. Any moisture that collects on the thawed container should be removed prior to use. Adhesives that appear to have separated should not be used.

Storage

Adhesive should be stored @ -40°C. The shelf life of the material is only valid when the material has been stored at the correct storage condition.

Availability

FeedBond adhesives are packaged in syringes or pots per customer specification. For the details, please contact our Customer Service or sales department.